

HIGH SPEED PULL TEST DEVICE AND METHOD

Abstract of the Disclosure

A device and method for tensile testing of the bond strength of an electrically conductive ball adhered to a substrate. A ball is gripped and moved at a speed in a direction substantially orthogonal to the plane of adherence. The substrate is abruptly halted by an abutment to impose a sudden load on the ball/substrate interface. Breaking force is measured by conventional means. During the test the substrate is lightly urged toward the ball to eliminate unwanted tensile forces.